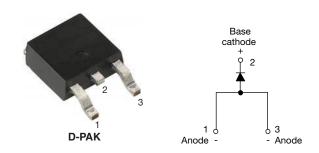
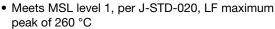


## High Voltage Surface Mount Input Rectifier Diode, 8 A



PRODUCT SUMMARY							
Package	D-PAK (TO-252AA)						
I <sub>F(AV)</sub>	8 A						
$V_{R}$	800 V, 1200 V						
V <sub>F</sub> at I <sub>F</sub>	1.1 V						
I <sub>FSM</sub>	150 A						
T <sub>J</sub> max.	150 °C						
Diode variation	Single die						

#### **FEATURES**





Material categorization:
 For definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

# ROHS COMPLIANT

#### **APPLICATIONS**

- · Input rectification
- Vishay Semiconductors switches and output rectifiers which are available in identical package outlines

#### **DESCRIPTION**

The 8EWS..SPbF rectifier high voltage series has been optimized for very low forward voltage drop, with moderate leakage. The glass passivation technology used has reliable operation up to 150 °C junction temperature.

The **high reverse voltage** range available allows design of input stage primary rectification with **outstanding voltage surge** capability.

OUTPUT CURRENT IN TYPICAL APPLICATIONS								
APPLICATIONS SINGLE-PHASE BRIDGE THREE-PHASE BRIDGE								
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 μm) copper	1.2	1.6						
Aluminum IMS, R <sub>thCA</sub> = 15 °C/W	2.5	2.8	А					
Aluminum IMS with heatsink, R <sub>thCA</sub> = 5 °C/W	5.5	6.5						

#### Note

•  $T_A = 55$  °C,  $T_J = 125$  °C, footprint 300 mm<sup>2</sup>

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL CHARACTERISTICS VALUES								
I <sub>F(AV)</sub>	Sinusoidal waveform at T <sub>C</sub> = 116 °C	8	A					
V <sub>RRM</sub>		800/1200	V					
I <sub>FSM</sub>		150	A					
V <sub>F</sub>	8 A, T <sub>J</sub> = 25 °C	1.10	V					
TJ		-55 to 150	°C					

VOLTAGE RATINGS								
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> AT 150 °C mA					
8EWS08SPbF	800	900	0.5					
8EWS12SPbF	1200	1300	0.5					





ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Maximum average forward current I <sub>F(</sub> ,		T <sub>C</sub> = 105 °C, 180° conduction half sine wave	8						
Maximum peak one cycle non-repetitive surge current	I <sub>FSM</sub>	10 ms sine pulse, rated V <sub>RRM</sub> applied	125	А					
		10 ms sine pulse, no voltage reapplied	150						
Maximum I <sup>2</sup> t for fusing	l <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied	78	A <sup>2</sup> s					
Maximum I-t for fusing		10 ms sine pulse, no voltage reapplied 110		A-5					
Maximum I <sup>2</sup> √t for fusing	I²√t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s					

ELECTRICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST COI	VALUES	UNITS			
Maximum forward voltage drop	$V_{FM}$	8 A, T <sub>J</sub> = 25 °C	1.1	V			
Forward slope resistance	r <sub>t</sub>	T <sub>.1</sub> = 150 °C	20	mΩ			
Threshold voltage	V <sub>F(TO)</sub>	1j = 150 C	0.82	V			
Maximum reverse leakage current		T <sub>J</sub> = 25 °C		0.05	mA		
waxiinum reverse leakage current	I <sub>RM</sub>	T <sub>J</sub> = 150 °C	V <sub>R</sub> = Rated V <sub>RRM</sub>	0.50	IIIA		

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to 150	°C			
Soldering temperature	T <sub>S</sub>		260				
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation	2.5	°C/W			
Typical thermal resistance, junction to ambient (PCB mount)	R <sub>thJA (1)</sub>		62				
Approximate weight			1	g			
Approximate weight			0.03	OZ.			
Marking device		Case style D-PAK (TO-252AA)	8EWS12S				

#### Note

<sup>(1)</sup> When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994



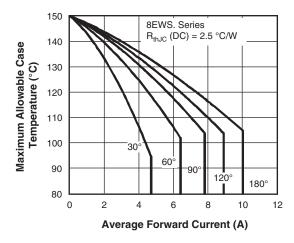


Fig. 1 - Current Rating Characteristics

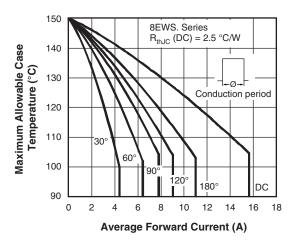


Fig. 2 - Current Rating Characteristics

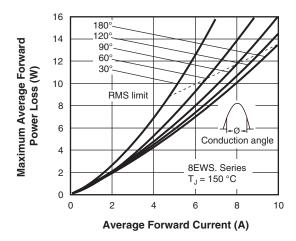


Fig. 3 - Forward Power Loss Characteristics

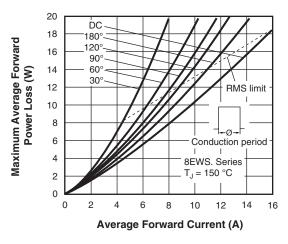


Fig. 4 - Forward Power Loss Characteristics

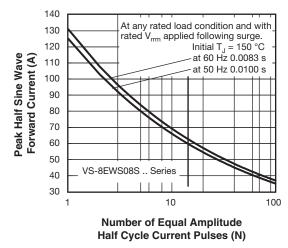


Fig. 5 - Maximum Non-Repetitive Surge Current

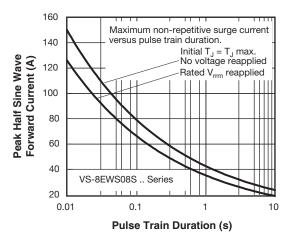


Fig. 6 - Maximum Non-Repetitive Surge Current

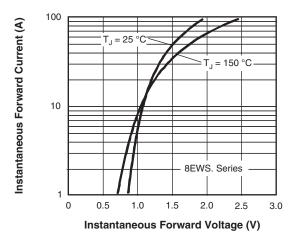


Fig. 7 - Forward Voltage Drop Characteristics

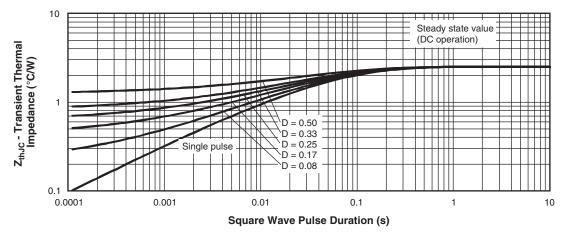
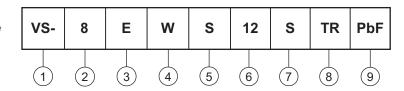


Fig. 8 - Thermal Impedance Z<sub>thJC</sub> Characteristics



#### **ORDERING INFORMATION TABLE**

**Device code** 



Vishay Semiconductors product

Current rating (8 = 8 A)

3 Circuit configuration:

E = Single diode

4 Package:

W = D-PAK

5 Type of silicon:

S = Standard recovery rectifier

08 = 800 V12 = 1200 V

Voltage ratings 6 7

S = Surface mountable

8 • TR = Tape and reel

• TRR = Tape and reel (right oriented)

• TRL = Tape and reel (left oriented)

9 PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS						
Dimensions <u>www.vishay.com/doc?95016</u>						
Part marking information	www.vishay.com/doc?95059					
Packaging information	www.vishay.com/doc?95033					



**INCHES** 

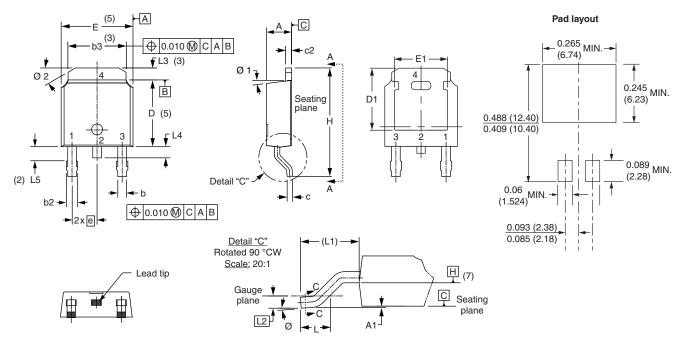
MIN.

MAX.

**NOTES** 

## **D-PAK (TO-252AA)**

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES		SYMBOL	MILLIM	IETERS	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES		STIVIDOL	MIN.	MAX.
Α	2.18	2.39	0.086	0.094			е	2.29	BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	
b3	4.95	5.46	0.195	0.215	3		L2	0.51	BSC	
С	0.46	0.61	0.018	0.024			L3	0.89	1.27	
c2	0.46	0.89	0.018	0.035			L4	-	1.02	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	
D1	5.21	-	0.205	-	3		Ø	0°	10°	
Е	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	

е	2.29 BSC		e 2.29 BSC 0.090 BSC		BSC	
Н	9.40	10.41	0.370	0.410		
L	1.40	1.78	0.055	0.070		
L1	2.74	2.74 BSC		0.108 REF.		
L2	0.51	BSC	0.020	BSC		
L3	0.89	1.27	0.035	0.050	3	
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060	2	
Ø	0°	10°	0°	10°		
Ø1	0°	15°	0°	15°	·	
Ø2	25°	35°	25°	35°	·	
	H L1 L2 L3 L4 L5 Ø	H 9.40 L 1.40 L1 2.74 L2 0.51 L3 0.89 L4 - L5 1.14 Ø 0° Ø1 0°	H 9.40 10.41  L 1.40 1.78  L1 2.74 BSC  L2 0.51 BSC  L3 0.89 1.27  L4 - 1.02  L5 1.14 1.52  Ø 0° 10°  Ø1 0° 15°	H         9.40         10.41         0.370           L         1.40         1.78         0.055           L1         2.74 BSC         0.108           L2         0.51 BSC         0.020           L3         0.89         1.27         0.035           L4         -         1.02         -           L5         1.14         1.52         0.045           Ø         0°         10°         0°           Ø1         0°         15°         0°	H 9.40 10.41 0.370 0.410  L 1.40 1.78 0.055 0.070  L1 2.74 BSC 0.108 REF.  L2 0.51 BSC 0.020 BSC  L3 0.89 1.27 0.035 0.050  L4 - 1.02 - 0.040  L5 1.14 1.52 0.045 0.060  Ø 0° 10° 0° 10°  Ø1 0° 15° 0° 15°	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- Outline conforms to JEDEC outline TO-252AA



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Vishay

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